

PRODUCT DATA SHEET

TACFlux® 571HF

Introduction

TACFlux® 571HF is a no-clean, halogen-free flux formulated for both hand soldering and rework. **TACFlux® 571HF** is compatible with typical Pb-free (SAC) and low-temp bismuth-containing and indium-containing alloys for PCB assembly applications. Benefits include:

- Halogen-free per IEC 61249-2-21 test method EN14582
- Clear post-reflow flux residue for no-clean applications
- Shelf life of up to 1 year

Properties

Industry Standard Test Results	
Test	Result
Flux Classification	ROLO
Halogen-Free per IEC 61249-2-21, Test Method EN14582	<900ppm Cl <900ppm Br <1,500ppm Total
Typical Viscosity*	12.5kcps
Typical Tack	135g
Typical Acid Value	130mg KOH/G
SIR (J-STD-004B)	Pass
ECM (J-STD-004B)	Pass
Flux-Induced Corrosion (Cu Mirror)	Pass
Corrosion	Pass

*Brookfield Cone & Plate (CP51, 5rpm, 5 minutes, 25°C).

Additional Test Results	
Test	Result
Appearance	Clear
Maximum Reflow Temperature	260°C
Reflow Atmosphere	Air or nitrogen
Shelf Life	1 year @ 0–30°C
Storage Condition	Stored @ 0–30°C (tip down for syringe or cartridge)

All information is for reference only.

Not to be used as incoming product specifications.

This product data sheet is provided for general information only. It is not intended, and shall not be construed, to warrant or guarantee the performance of the products described which are sold subject exclusively to written warranties and limitations thereon included in product packaging and invoices. All Indium Corporation's products and solutions are designed to be commercially available unless specifically stated otherwise.

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

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Packaging

TACFlux® 571HF is available in 10 and 30cc syringes or 100g jars; however, other packaging can be provided to meet specific requirements.

Cleaning

TACFlux® 571HF is designed for no-clean applications. If necessary, the flux can be removed by using a commercially available flux cleaner.

Reflow

Peak reflow temperature should be <260°C in an air or nitrogen atmosphere.

Storage

TACFlux® 571HF syringes and cartridges should be stored tip down at 0–30°C. If refrigerated, **TACFlux® 571HF** should be thawed for 4 hours at room temperature before using.

Technical Support

Indium Corporation's internationally experienced engineers provide in-depth technical assistance to our customers. Thoroughly knowledgeable in all facets of Materials Science as it applies to the electronics and semiconductor sectors, Technical Support Engineers provide expert advice in solder properties, alloy compatibility and selection of solder preforms, wire, ribbon, and paste. Indium Corporation's Technical Support Engineers provide rapid response to all technical inquiries.

Safety Data Sheets

The SDS for this product can be found online at <http://www.indium.com/sds>



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